

8-BIT SINGLE-CHIP MICROCONTROLLER

The 78K0/KE2 products are 8-bit single-chip microcontrollers of the 78K0 series.

These microcontrollers feature Single-voltage Self-programming Flash memory and many peripherals.

FEATURES

- 78K0 CPU core, 8-bit CISC architecture
- Flash EEPROM and RAM sizes

Product name	Item	Program memory (Flash EEPROM)	Data memory (RAM)
μ PD78F0537		128K bytes (Flash)	7K bytes
μ PD78F0536		96K bytes (Flash)	5K bytes
μ PD78F0535		60K bytes (Flash)	3K bytes
μ PD78F0534		48K bytes (Flash)	2K bytes
μ PD78F0533		32K bytes (Flash)	1K bytes
μ PD78F0532		24K bytes (Flash)	1K bytes
μ PD78F0531		16K bytes (Flash)	768 bytes

Minimum instruction cycle

0.1 μ s (20MHz@4.0V to 5.5V)

0.2 μ s (10MHz@2.7V to 5.5V)

0.4 μ s (5MHz@1.8V to 5.5V)

Clock

• MAIN CLOCK

- Internal Ring-oscillator 8MHz (Typ.)
- Ceramic/Crystal Oscillator/External CLK (2MHz to 20MHz)
(Instruction execution time = 100ns(min.) @20MHz)

• SUB CLOCK

- 32.768KHz Crystal oscillator/ External CLK

• WDT CLOCK

- Internal Ring-oscillator 240KHz (Typ.)

Peripherals.

• On-Chip Power-On-Clear (POC) Circuit

• Low-Voltage Detector (LVI) Circuit

• Timer

- 16bit Timer 2ch (1ch: μ PD78F0533/0532/0531)
- 8bit Timer 4ch
- Watch Timer
- Watchdog Timer (Operable with 240KHz Ring-OSC)

• Serial Interface

- UART/CSI 1ch
- UART (with LIN-bus) 1ch
- CSI 1ch (μ PD78F0534/0535/0536/0537 only)
- IIC 1ch

• Key Interrupt 8ch

• AD CONVERTER

- 10-bit resolution A/D converter 8ch

• I/O PORT

Total : 55

CMOS I/O : 50

CMOS Output: 1

N-ch O.D I/O: 4

• MULTIPLIER/DIVIDER

- 16bit x 16bit, 32bit / 16bit
(μ PD78F0534/0535/0536/0537 only)

• Other

- Self programming
- PCL / BUZ OUTPUT
- On-chip debug function (Product name is undecided)

Interrupt

- Internal 19ch (16ch: μ PD78F0531/0532/0533)
- External 9ch

Operation Voltage

1.8V to 5.5V

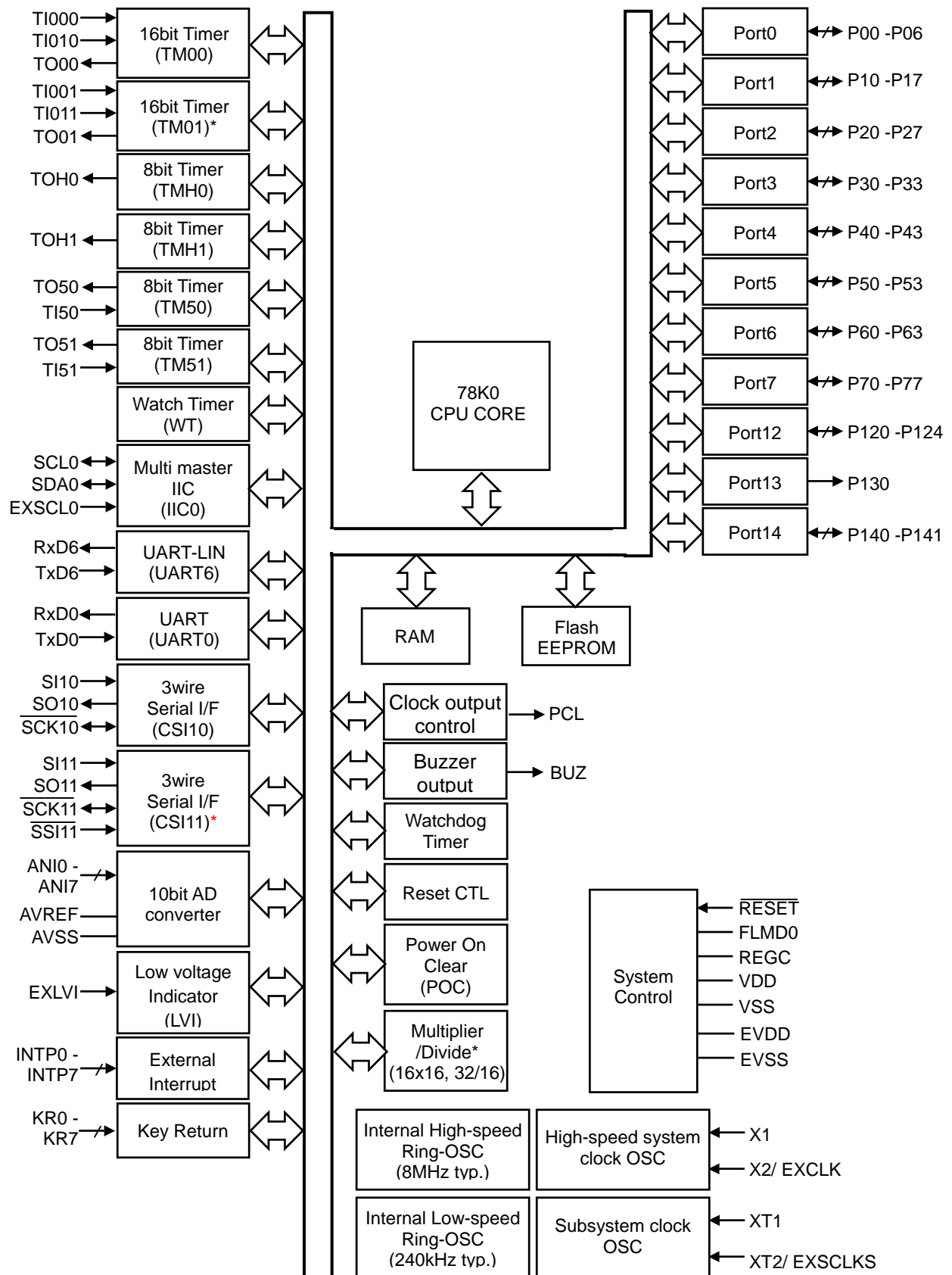
Package

- 64-pin LQFP(10mm x 10mm, 0.5mm pitch)
- 64-pin LQFP(12mm x 12mm, 0.65mm pitch)
- 64-pin QFP(14mm x 14mm, 0.8mm pitch)

This information contained in this document is being issued in advance of the production cycle for the product. The parameters for the product may change before final production or NEC Electronics Corporation, at its own discretion,, may withdraw the product prior to its production. Not all products and/ or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.

1. Block Diagram

Fig. 78K0/KE2



*: μPD78F0537/0536/0535/0534 only

2. Pin Lay Out

78K0/KE2

64-pin plastic QFP (14 x 14mm 0.8mm pitch)

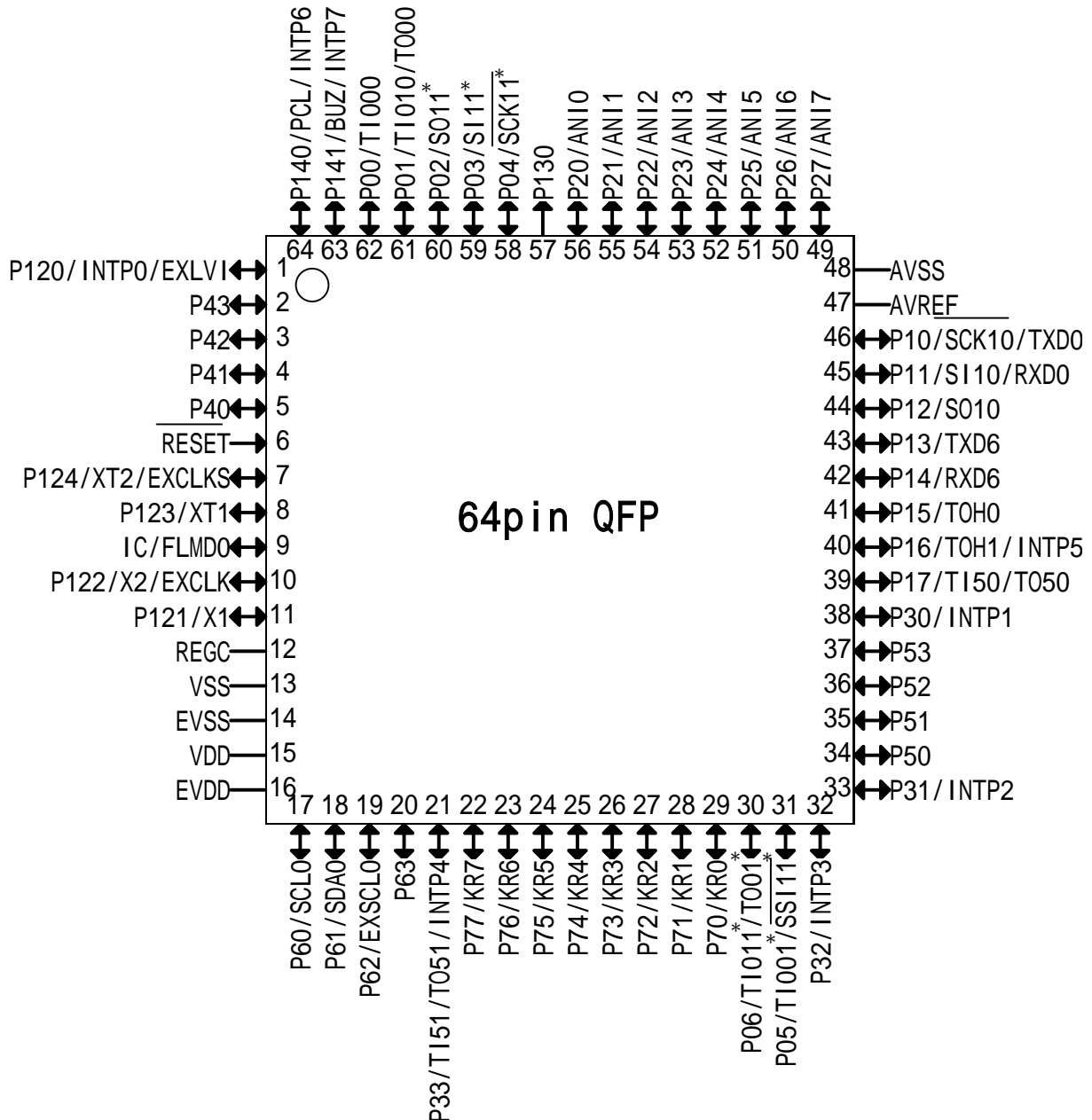
μPD78F0537GC-UBS, μPD78F0536GC-UBS, μPD78F0535GC-UBS
 μPD78F0534GC-UBS, μPD78F0533GC-UBS, μPD78F0532GC-UBS
 μPD78F0531GC-UBS

64-pin plastic LQFP (12 x 12mm 0.65mm pitch)

μPD78F0537GK-UBT, μPD78F0536GK-UBT, μPD78F0535GK-UBT
 μPD78F0534GK-UBT, μPD78F0533GK-UBT, μPD78F0532GK-UBT
 μPD78F0531GK-UBT

64-pin plastic LQFP (10 x 10mm 0.5mm pitch)

μPD78F0537GB-UEU, μPD78F0536GB-UEU, μPD78F0535GB-UEU,
 μPD78F0534GB-UEU, μPD78F0533GB-UEU, μPD78F0532GB-UEU,
 μPD78F0531GB-UEU,



*: μPD78F0537/0536/0535/0534 only

3. Pin Function

Table (1/2)

PIN NAME	Function
VDD	Positive power supply except for ports (except P20-P27 and P121-P124) and AD converter
VSS	Ground potential except for ports(except P20-P27 and P121-P124) and AD converter
EVDD	Positive power supply for ports (except P20-P27 and P121-P124)
EVSS	Ground potential for ports (except P20-P27 and P121-P124)
RESET	System reset input
FLMD0	Flash EEPROM programming mode setting
REGC	Connecting regulator stabilization capacitor. Connect to ground via a capacitor (0.47 μ F)
AVREF	A/D converter analog power supply and power supply for P20-P27
AVSS	Ground potential for A/D converter and P20 - P27.
P00 /TI00	I/O port External count clock input to 16-bit timer/event counter 00 Capture trigger input to capture registers (CR000, CR010) of 16-bit timer/event counter 00 (TM00)
P01 /TI010 /TO00	I/O port Capture trigger input to capture register (CR000) of 16-bit timer/event counter 00 (TM00) 16-bit timer/event counter 00 output (TM00)
P02 /SO11*	I/O port Serial data output from serial interface (CSI11)
P03 /SI11*	I/O port Serial data input to serial interface (CSI11)
P04 /SCK11*	I/O port Clock input/ output for serial interface (CSI11)
P05 /TI001* /SSI11*	I/O port External count clock input to 16-bit timer/event counter 01 Capture trigger input to capture registers (CR001, CR011) of 16-bit timer/event counter 01 (TM01) Chip select input for serial interface (CSI11)
P06 /TI011* /TO01*	I/O port Capture trigger input to capture register (CR001) of 16-bit timer/event counter 01 (TM01) 16-bit timer/event counter 01 output (TM01)
P10 /SCK10 /TXD0	I/O port Clock input/ output for serial interface (CSI10) Serial data output from asynchronous serial interface (UART0)
P11 /SI10 /RXD0	I/O port Serial data input to serial interface (CSI10) Serial data input to asynchronous serial interface (UART0)
P12 /SO10	I/O port Serial data output form serial interface (CSI10)
P13 /TXD6	I/O port Serial data output from asynchronous serial interface (UART6)
P14 /RXD6	I/O port Serial data input from asynchronous serial interface (UART6)
P15 /TOH0	I/O port 8-bit timer H0 output (TMH0)
P16 /TOH1 /INTP5	I/O port 8-bit timer H1 output (TMH1) External interrupt request input with specifiable valid edges
P17 /TI50 /TO50	I/O port External count clock input to 8-bit timer/event counter 50 (TM50) 8-bit timer/event counter 50 output (TM50)

*: μ PD78F0537/0536/0535/0534 only

Table(2/2)

PIN NAME	Function
P20- P27 / ANI0- ANI7	I/O ports A/D converter analog input
P30/INTP1	I/O port
P31/INTP2	External interrupt request input with specifiable valid edges
P32/INTP3	
P33	I/O port
/T151	External count clock input to 8-bit timer/event counter 51(TM51)
/TO51	8-bit timer/event counter 51output (TM51)
/INTP4	External interrupt request input with specifiable valid edges
P40 - P43	I/O port
P50 - P53	I/O port
P60	I/O port (N-ch Open drain)
/SCL0	Clock input/ output for serial interface (IIC0)
P61	I/O port (N-ch Open drain)
/SDA0	Serial data input/ output for serial interface (IIC0)
P62	I/O port (N-ch Open drain)
/EXSCL0	External clock input for serial interface (IIC0)
P63	I/O port (N-ch Open drain)
P70 – P77	I/O ports
/KR0 – KR7	Key interrupt input
P120	I/O port
/INTP0	External interrupt request input with specifiable valid edges
/EXLVI	Reference voltage input for Low voltage Indicator
P121	I/O port (An external oscillation circuit is not used)
/X1	Connecting resonator for main system clock oscillation
P122	I/O port (An external oscillation circuit is not used)
/X2	Connecting resonator for main system clock oscillation
/EXCLK	External clock input for main system clock
P123	I/O port (An external oscillation circuit is not used)
/XT1	Connecting resonator for subsystem clock oscillation
P124	I/O port (An external oscillation circuit is not used)
/XT2	Connecting resonator for subsystem clock oscillation
/EXCLKS	External clock input for subsystem clock
P130	Output port
P140	I/O port
/PCL	Clock output
/INTP6	External interrupt request input with specifiable valid edge
P141	I/O port
/BUZ	Buzzer output
/INTP7	External interrupt request input with specifiable valid edge
/BUSY0	Busy signal input for serial interface (AUTOCSI)

4. Memory space

78K0/KE2 have 64kB linear address area.

To access more than 64KB ROM area, 96KB and 128KB ROM products have BANK type ROM at address of 8000H to C000H. All BANK ROM size is 16KB.

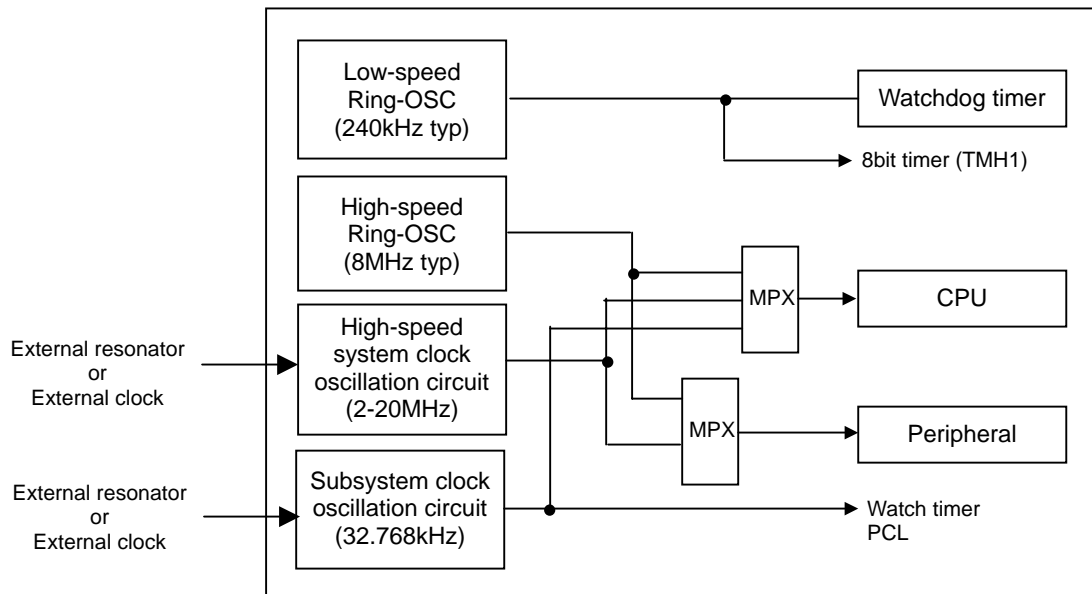
Products	ROM size	Common ROM	Bank ROM	
		Address	Address	Number of Bank
μPD78F0537	128KB	0000H-7FFFH (32KB)	8000H-BFFFH (16KB)	6
μPD78F0536	96KB	0000H-7FFFH (32KB)	8000H-BFFFH (16KB)	4
μPD78F0535	60KB	0000H-EFFFH (60KB)	-	-
μPD78F0534	48KB	0000H-BFFFH (48KB)	-	-
μPD78F0533	32KB	0000H-7FFFH (32KB)	-	-
μPD78F0532	24KB	0000H-5FFFH (24KB)	-	-
μPD78F0531	16KB	0000H-3FFFH (16KB)	-	-

5. Clock

78K0/KE2 have 2 type internal Ring-OSC and 2 type external resonator oscillation circuit.

78K0/KE2 can be operated high-speed internal Ring-OSC only. Low-speed Ring-OSC can connect to Watch dog timer and 8bit timer (TMH1) only for high secure.

Fig. Clock connecting block image



6. Outline of Functions of KE2

		μ PD78F0531	μ PD78F0532	μ PD78F0533
Internal Memory (Byte)	Flash Memory	16 K	24 K	32 K
	Bank	-		
	High Speed RAM	768	1K	
	Extend RAM	-		
Main System Clock	Ceramic/Crystal	- 2 to 20 MHz: $V_{DD} = 4.0$ to 5.5 V - 2 to 10 MHz: $V_{DD} = 2.7$ to 5.5 V - 2 to 5 MHz: $V_{DD} = 1.8$ to 5.5 V		
	Internal Ring-OSC	- 8 MHz(TYP.)		
Sub System Clock		- 32.768 kHz(TYP.)		
Internal Low Speed Ring-OSC (For TMH1, WDT)		- 240 kHz(TYP.)		
Minimum Instruction Cycle		- 0.1 μ s (Ceramic/ Crystal Operation $f_{XH} = 20$ MHz $V_{DD} = 4.0$ to 5.5 V)		
I/O		Total	:55	
		- CMOS I/O	:50	
		- CMOS Out	:1	
		- N-ch O.D.	:4	
Timer		- 16 Bit Timer/Event Counter:1ch - 8 Bit Timer/Event Counter:2ch - 8 bit Timer:2ch - Watch Timer:1ch - Watch Dog Timer:1ch		
Timer Output		-5(PWM:34)		
PCL output		- 156.25kHz, 312.5kHz, 615kHz, 1.25MHz, 2.5MHz, 5MHz, 10MHz ($f_{PRS} = 20$ MHz)		
Buzzer Output		- 2.44 kHz, 4.88 kHz, 9.77 kHz, 19.54 kHz($f_{PRS} = 20$ MHz)		
A/D Converter		- 10bit x 8ch		
Serial Interface		- UART (with LIN-bus):1ch - CSI/ UART:1ch - I ² C:1ch		
Multiplier/Divider		-		
Interrupt	Internal	16		
	External	9		
Key Return		8ch		
On Chip Debug Function		Product name is undecided.		
Voltage Range		$V_{DD} = 1.8$ to 5.5 V		
Operation temperature		$T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$		
Package		- 64pin LQFP(10x10) 0.5mm pitch - 64pin LQFP(12x12) 0.65mm pitch - 64pin QFP(14x14) 0.8mm pitch		

		μ PD78F0534	μ PD78F0535	μ PD78F0536	μ PD78F0537
Internal Memory (Byte)	Flash Memory	48 K	60 K	96 K	128 K
	Bank	-	-	4	6
	High Speed RAM	1K			
	Extend RAM	1 K	2 K	4 K	6 K
Main System Clock	Ceramic/Crystal	- 2 to 20 MHz: $V_{DD} = 4.0$ to 5.5 V - 2 to 10 MHz: $V_{DD} = 2.7$ to 5.5 V - 2 to 5 MHz: $V_{DD} = 1.8$ to 5.5 V			
	Internal Ring-OSC	- 8 MHz(TYP.)			
Sub System Clock		- 32.768 kHz(TYP.)			
Internal Low Speed Ring-OSC (For TMH1, WDT)		- 240 kHz(TYP.)			
Minimum Instruction Cycle		- $0.1 \mu s$ (Ceramic/ Crystal Operation $f_{XH} = 20$ MHz $V_{DD} = 4.0$ to 5.5 V)			
I/O		Total	:55		
		- CMOS I/O	:50		
		- CMOS Out	:1		
		- N-ch O.D.	:4		
Timer		- 16 Bit Timer/Event Counter:2ch - 8 Bit Timer/Event Counter:2ch - 8 bit Timer:2ch - Watch Timer:1ch - Watch Dog Timer:1ch			
Timer Output		-6(PWM:4)			
PCL output		- 156.25kHz, 312.5kHz, 615kHz, 1.25MHz, 2.5MHz, 5MHz, 10MHz ($f_{PRS} = 20$ MHz)			
Buzzer Output		- 2.44 kHz, 4.88 kHz, 9.77 kHz, 19.54 kHz($f_{PRS} = 20$ MHz)			
A/D Converter		- 10bit x 8ch			
Serial Interface		- UART (with LIN-bus):1ch - CSI/ UART:1ch - CSI:1ch - I ² C:1ch			
Multiplier/Divider		16bitx16bit, 32bit/8bit			
Interrupt	Internal	19			
	External	9			
Key Return		8ch			
On Chip Debug Function		Product name is undecided.			
Voltage Range		$V_{DD} = 1.8$ to 5.5 V			
Operation temperature		$T_a = -40^{\circ}C$ to $+85^{\circ}C$			
Package		- 64pin LQFP(10x10) 0.5mm pitch - 64pin LQFP(12x12) 0.65mm pitch - 64pin QFP(14x14) 0.8mm pitch			

7. Electrical specification of KE2 (Target)

Caution These specifications show target values, which may change after device evaluation. The operating voltage range may also change.

Absolute Maximum Ratings(T_A = 25°C) (1/2)

Parameter	Symbol	Conditions	Ratings	Unit	
Supply voltage	V _{DD}		-0.5 to +6.5	V	
	EV _{DD}		-0.5 to +6.5	V	
	V _{SS}		-0.5 to +0.3	V	
	EV _{SS}		-0.5 to +0.3	V	
	AV _{REF}		-0.5 to +6.5	V	
	AV _{SS}		-0.5 to +0.3	V	
Input voltage	V _{I1}		-0.3 to V _{DD} = EV _{DD} +0.3 ^{Note}	V	
	V _{I2}	P60-P63(N-ch open drain)	-0.3 to +6.5	V	
Output voltage	V _O		-0.3 to V _{DD} = EV _{DD} +0.3 ^{Note}	V	
Analog input voltage	V _{AN}		-0.3 to AV _{REF} +0.3 ^{Note}	V	
Output current, high	I _{OH}	Per pin	-10	mA	
		Total of all pins -80 mA	P00-P04, P40-P43, P120-P124, P130, P140-P141	-25	mA
		P05-P06, P10-P17,P30-P33, P50-P53,P60-P63, P70-P77	-55	mA	

Note Must be 6.5 V or lower.

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

Absolute Maximum Ratings($T_A = 25^{\circ}\text{C}$) (2/2)

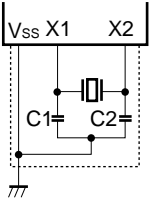
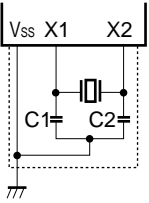
Parameter	Symbol	Conditions	Ratings	Unit	
Output current, low	I _{oL}	Per pin	30	mA	
		Total of all pins 200 mA	P00-P04, P40-P43, P120-P124, P130, P140-P141	60	mA
			P05-P06, P10-P17,P30-P33, P50-P53,P60-P63, P70-P77	140	mA
Operating ambient temperature	T _A	In normal operation mode	-40 to +85	°C	
		In flash memory programming mode			
Storage temperature	T _{stg}		-65 to +150	°C	

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

High-Speed System Clock (Crystal/Ceramic) Oscillator Characteristics

($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} = EV_{DD} \leq 5.5\text{ V}$, $2.3\text{ V} \leq AV_{REF} \leq V_{DD} = EV_{DD}$, $V_{SS} = EV_{SS} = AV_{SS} = 0\text{ V}$)

Resonator	Recommended Circuit	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Ceramic resonator		Oscillation frequency(f_{XH}) ^{Note}	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	2.0		20.0	MHz
			$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$	2.0		10.0	
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$	2.0		5.0	
Crystal resonator		Oscillation frequency(f_{XH}) ^{Note}	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	2.0		20.0	MHz
			$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$	2.0		10.0	
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$	2.0		5.0	

Note Indicates only oscillator characteristics. Refer to AC Characteristics for instruction execution time.

Cautions 1. When using the high-speed system clock oscillator, wire as follows in the area enclosed by the broken lines in the above figures to avoid an adverse effect from wiring capacitance.

- Keep the wiring length as short as possible.
- Do not cross the wiring with the other signal lines.
- Do not route the wiring near a signal line through which a high fluctuating current flows.
- Always make the ground point of the oscillator capacitor the same potential as Vss.
- Do not ground the capacitor to a ground pattern through which a high current flows.
- Do not fetch signals from the oscillator.

2. Since the CPU is started by the Ring-OSC after reset is released, check the oscillation stabilization time of the high-speed system clock using the oscillation stabilization time status register (OSTC). Determine the oscillation stabilization time of the OSTC register and oscillation stabilization time select register (OSTS) after sufficiently evaluating the oscillation stabilization time with the resonator to be used.

Remark For the resonator selection and oscillator constant, customers are requested to either evaluate the oscillation themselves or apply to the resonator manufacturer for evaluation.

Ring-OSC Oscillator Characteristics

($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} = EV_{DD} \leq 5.5\text{ V}$, $2.3\text{ V} \leq AV_{REF} \leq V_{DD} = EV_{DD}$, $V_{SS} = EV_{SS} = AV_{SS} = 0\text{ V}$)

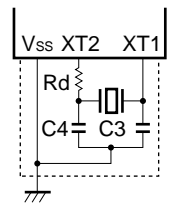
Resonator	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
8 MHz Ring-OSC oscillator	High-speed Ring-OSC Oscillation frequency(f_{RH}) ^{Note1}	$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	7.6 ^{Note2}	8.0 ^{Note2}	8.4 ^{Note2}	MHz
		$1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	T.B.D	8.0 ^{Note2}	T.B.D	
240 kHz Ring-OSC oscillator	Low-speed Ring-OSC Oscillation frequency(f_{RL})	$2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	216	240	264	kHz
		$1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	T.B.D	240	T.B.D	

Note 1. Indicates only oscillator characteristics. Refer to AC Characteristics for instruction execution time.

2. This is the frequency in the case of $RSTS(RCM.7)=1$. This is 5 MHz(TYP.) in the case of $RSTS=0$.

Subsystem Clock Oscillator Characteristics

($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} = EV_{DD} \leq 5.5\text{ V}$, $2.3\text{ V} \leq AV_{REF} \leq V_{DD} = EV_{DD}$, $V_{SS} = EV_{SS} = AV_{SS} = 0\text{ V}$)

Resonator	Recommended Circuit	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Crystal resonator		Oscillation frequency(f_{sub}) ^{Note}		32	32.768	35	kHz

Note Indicates only oscillator characteristics. Refer to AC Characteristics for instruction execution time.

Cautions 1. When using the subsystem clock oscillator, wire as follows in the area enclosed by the broken lines in the above figures to avoid an adverse effect from wiring capacitance.

- Keep the wiring length as short as possible.
- Do not cross the wiring with the other signal lines.
- Do not route the wiring near a signal line through which a high fluctuating current flows.
- Always make the ground point of the oscillator capacitor the same potential as Vss.
- Do not ground the capacitor to a ground pattern through which a high current flows.
- Do not fetch signals from the oscillator.

2. The subsystem clock oscillator is designed as a low-amplitude circuit for reducing power consumption, and is more prone to malfunction due to noise than the high-speed system clock oscillator. Particular care is therefore required with the wiring method when the subsystem clock is used.

Remark For the resonator selection and oscillator constant, customers are requested to either evaluate the oscillation themselves or apply to the resonator manufacturer for evaluation.

DC Characteristics (1/4)

($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} = EV_{DD} \leq 5.5\text{ V}$, $V_{SS} = EV_{SS} = AV_{SS} = 0\text{ V}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit		
Output current, high	I _{OH1}	Per pin of P00-P06, P10-P17, P30-P33, P40-P43, P50-P53, P70-P77, P120-124, P130, P140-P141	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$			-3.0	mA	
			$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$			-2.5		
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$			-1.0		
		Total of P00-P04, P40-P43, P120, P130, P140-P141	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$				-20.0	mA
			$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$				-10.0	
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$				-5.0	
		Total of P05-P06, P10-P17, P30-P33, P50-P53, P70-P77	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$				-30.0	mA
			$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$				-19.0	
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$				-10.0	
		Total of all pins	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$				-50.0	mA
			$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$				-29.0	
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$				-15.0	
		I _{OH2}	Per pin of P20-P27, P121-P124 ^{Note}	$1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$			-100	μA
	Output current, low	I _{OL1}	Per pin of P00-P06, P10-P17, P30-P33, P40-P43, P50-P53, P70-P77, P120, P130, P140-P141	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$			8.5	mA
				$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$			5.0	
$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$						2.0		
Per pin of P60-P63			$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$				15.0	mA
			$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$				5.0	
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$				2.0	
Total of P00-P04, P40-P43, P120, P130, P140-P141			$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$				20.0	mA
			$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$				15.0	
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$				9.0	
Total of P05-P06, P10-P17, P30-P33, P50-P53, P70-P77			$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$				45.0	mA
			$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$				35.0	
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$				20.0	
Total of all pins		$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$				65.0	mA	
		$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$				50.0		
		$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$				29.0		
	I _{OL2}	Per pin of P20-P27, P121-P124 ^{Note}	$1.8\text{ V} \leq V_{DD} \leq 5.5\text{ V}$			400	μA	

Note When used as digital input ports, set $AV_{REF} = V_{DD} = EV_{DD}$.

Caution This specification is Duty = 70% condition of I_{OH} and I_{OL}.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

DC Characteristics (2/4)

($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} = EV_{DD} \leq 5.5\text{ V}$, $V_{SS} = EV_{SS} = AV_{SS} = 0\text{ V}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input voltage, high	V_{IH1}	P02, P12, P13, P15, P40-P43, P50-P53, P60-P63, P121-P124	$0.7V_{DD}$		V_{DD}	V
	V_{IH2}	P00, P01, P03-P06, P10-P11, P14, P16-P17, P30-P33, P70-P77, P120, P140-P141, RESET	$0.8V_{DD}$		V_{DD}	V
	V_{IH3}	P20-P27 ^{Note}	$0.7AV_{REF}$		AV_{REF}	V
Input voltage, low	V_{IL1}	P02, P12, P13, P15, P40-P43, P50-P53, P60-P63, P121-P124	0		$0.3V_{DD}$	V
	V_{IL2}	P00, P01, P03-P06, P10-P11, P14, P16-P17, P30-P33, P70-P77, P120, P140-P141, RESET	0		$0.2V_{DD}$	V
	V_{IL3}	P20-P27 ^{Note}	0		$0.3AV_{REF}$	V

Note When used as digital input ports, set $AV_{REF} = V_{DD} = EV_{DD}$.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

DC Characteristics (3/4)

($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} = EV_{DD} \leq 5.5\text{ V}$, $V_{SS} = EV_{SS} = AV_{SS} = 0\text{ V}$)

Parameter	Symbol	Conditions			MIN.	TYP.	MAX.	Unit
Output voltage, high	V _{OH1}	I _{OH} = -3.0 mA	P00-P06, P10-P17, P30-P33, P40-P43, P50-P53, P70-P77, P120, P130, P140, P141	4.0V ≤ V _{DD} ≤ 5.5V	V _{DD} -0.7			V
		I _{OH} = -2.5 mA		2.7 V ≤ V _{DD} ≤ 5.5V	V _{DD} -0.5			V
		I _{OH} = -1.0 mA		1.8 V ≤ V _{DD} ≤ 5.5V	V _{DD} -0.5			V
	V _{OH2}	I _{OH} = -100 μA	P20-P27	1.8 V ≤ V _{DD} ≤ 5.5 V AV _{REF} = V _{DD} = EV _{DD}	V _{DD} -0.5			V
Output voltage, low	V _{OL1}	I _{OL} = 8.5 mA	P00-P06, P10-P17, P30-P33, P40-P43, P50-P53, P70-P77, P120, P130, P140, P141	4.0V ≤ V _{DD} ≤ 5.5V			0.7	V
		I _{OL} = 1.0 mA		2.7 V ≤ V _{DD} ≤ 5.5V			0.5	V
		I _{OL} = 0.5 mA		1.8 V ≤ V _{DD} ≤ 5.5V			0.4	V
	V _{OL2}	I _{OL} = 400 μA	P20-P27	1.8 V ≤ V _{DD} ≤ 5.5 V AV _{REF} = V _{DD} = EV _{DD}			0.4	V
	V _{OL3}	I _{OL} = 15.0 mA	P60-P63	4.0V ≤ V _{DD} ≤ 5.5V			2.0	V
		I _{OL} = 5.0 mA				0.4	V	
		I _{OL} = 3.0 mA		2.7 V ≤ V _{DD} ≤ 5.5V			0.4	V
		I _{OL} = 2.0 mA		1.8 V ≤ V _{DD} ≤ 5.5V			0.4	V
Input leakage current, high	I _{LIH1}	V _i = V _{DD} = EV _{DD}	P00-P06, P10-P17, P30-P33, P40-P43, P50-P53, P70-P77, P120-P124, P130, P140, P141				1	μA
	I _{LIH2}	V _i = AV _{REF}	P20-P27				1	μA
	I _{LIH3}	V _i = V _{DD} = EV _{DD}	X1, X2, XT1, XT2 (When use External oscillator)				20	μA
Input leakage current, low	I _{LIL1}	V _i = V _{SS} = EV _{SS}	P00-P06, P10-P17, P30-P33, P40-P43, P50-P53, P70-P77, P120-P124, P130, P140, P141				-1	μA
	I _{LIL2}	V _i = AV _{REF}	P20-P27				-1	μA
	I _{LIL3}	V _i = V _{SS} = EV _{SS}	X1, X2, XT1, XT2 (When use External oscillator)				-20	μA
Pull-up resistance value	R _U	V _i = V _{DD} = EV _{DD}			10	20	100	kΩ
FLMD0 supply voltage	V _{IL}	In normal operation mode			0		0.2V _{DD}	V
	V _{IH}	In flash memory programming mode			0.8V _{DD}		V _{DD}	V

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

DC Characteristics (4/4)

($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} = EV_{DD} \leq 5.5\text{ V}$, $2.3\text{ V} \leq AV_{REF} \leq V_{DD}$, $V_{SS} = EV_{SS} = AV_{SS} = 0\text{ V}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Supply current ^{Note1}	I _{DD1}	Operation mode	$f_{XH} = 20\text{ MHz}$ ^{Note2} , $V_{DD} = 5.0\text{ V}$		4.7	5.8	mA
			$f_{XH} = 10\text{ MHz}$ ^{Note2} , $V_{DD} = 5.0\text{ V}$ ^{Note3}		2.5	3.5	mA
			$f_{XH} = 5\text{ MHz}$ ^{Note2} , $V_{DD} = 3.0\text{ V}$ ^{Note3}		1.5	2.2	mA
			$f_{RH} = 8\text{ MHz}$ ^{Note2} , $V_{DD} = 5.0\text{ V}$		1.9	2.7	mA
			$f_{SUB} = 32.768\text{ kHz}$ ^{Note2} , $V_{DD} = 5.0\text{ V}$		17	T.B.D.	μA
	I _{DD2}	HALT mode	$f_{XH} = 20\text{ MHz}$ ^{Note2} , $V_{DD} = 5.0\text{ V}$		2.2	2.6	mA
			$f_{XH} = 10\text{ MHz}$ ^{Note2} , $V_{DD} = 5.0\text{ V}$ ^{Note3}		1.0	1.2	mA
			$f_{XH} = 5\text{ MHz}$ ^{Note2} , $V_{DD} = 3.0\text{ V}$ ^{Note3}		0.55	0.65	mA
			$f_{RH} = 8\text{ MHz}$ ^{Note2} , $V_{DD} = 5.0\text{ V}$		0.6	0.65	mA
			$f_{SUB} = 32.768\text{ kHz}$ ^{Note2} , $V_{DD} = 5.0\text{ V}$		3.5	T.B.D.	μA
	I _{DD3}	STOP mode	$V_{DD} = EV_{DD} = 5.0\text{ V}$		1	20	μA
	I _{ADC}	A/D converter operating current	A/D converter operating		0.57	1.3	mA
			A/D converter not operating		T.B.D.	T.B.D.	mA
	I _{WDT}	Watchdog Time operating current	240 kHz Ring-OSC operating		5	10	μA
	I _{LVI}	LVI operating current			9	T.B.D.	μA

- Notes**
1. Total current flowing through the internal power supply (V_{DD}).
 2. Input square-wave
 3. When AMPH(OSCCTL.0) = 0.

- Remark**
1. f_{XH} : High-Speed System Clock oscillation frequency (X1 clock oscillation frequency or External main system clock frequency).
 2. f_{RH} : High-speed Ring-OSC oscillation frequency.
 3. f_{SUB} : Subsystem Clock oscillation frequency (XT1 clock oscillation frequency or External subsystem clock frequency).

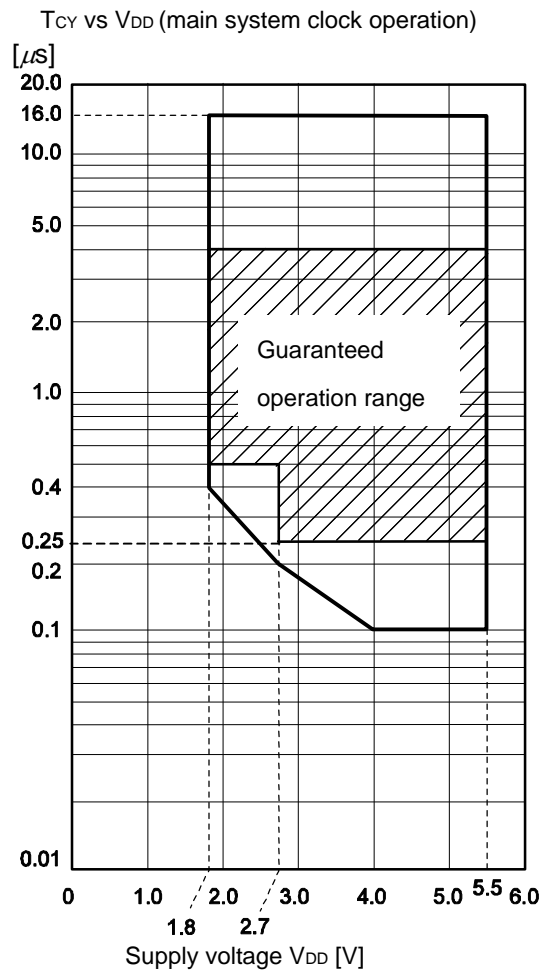
AC Characteristics

(1)Basic operation

($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} = EV_{DD} \leq 5.5\text{ V}$, $2.3\text{ V} \leq AV_{REF} \leq V_{DD} = EV_{DD}$, $V_{SS} = EV_{SS} = AV_{SS} = 0\text{ V}$)

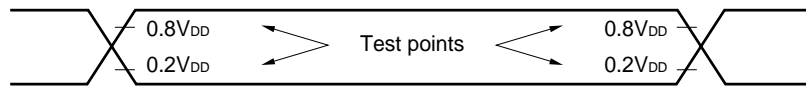
Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit	
Instruction cycle (minimum instruction execution time)	T _{CY}	Main system clock(f _{XP}) operation	High-speed system clock(f _{XH})	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	0.1		16	μs
				$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$	0.2		16	μs
				$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$	0.4		16	μs
			High-speed Ring-OSC clock(f _{RH})	$2.7\text{ V} \leq V_{DD} < 5.5\text{ V}$	0.25		4	μs
				$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$	0.5		4	μs
		Subsystem clock(f _{SUB})operation		114	122	125	μs	
External main system clock frequency	f _{EXCLK}	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$		2.0		20.0	MHz	
		$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$		2.0		10.0	MHz	
		$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$		2.0		5.0	MHz	
External main system clock input high-/low-level width	t _{EXCLKH} ,			(1/f _{EXCLK} x 1/2) - 1			ns	
	t _{EXCLKL}							
External subsystem clock frequency	f _{EXCLKS}			32	32.768	35	kHz	
External subsystem clock input high-/low-level width	t _{EXCLKSH} ,			(1/f _{EXCLKS} x 1/2) - 5			ns	
	t _{EXCLKSL}							
TI000, TI010, TI010 ^{Note3} , TI011 ^{Note3} input high-level width, low-level width	t _{TIH0} ,	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$		$2/f_{sam} + 0.1$ ^{Note1}			μs	
	t _{TIL0}	$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$			$2/f_{sam} + 0.2$ ^{Note1}			
TI50, TI51 input frequency	f _{TI5}	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$				10	MHz	
		$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$				10	MHz	
		$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$				5	MHz	
TI50, TI51 input high-level width, low-level width	t _{TIH5} ,	$4.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$		50			ns	
		t _{TIL5}	$2.7\text{ V} \leq V_{DD} < 4.0\text{ V}$		50	ns		
			$1.8\text{ V} \leq V_{DD} < 2.7\text{ V}$		100	ns		
Interrupt input high-level width, low-level width	t _{INTH} ,			1			μs	
	t _{INTL}							
Key return input low-level width	t _{KR}			250			ns	
RESET low-level width	t _{RSL}			10 ^{Note2}			μs	

- Notes**
1. Selection of $f_{sam} = f_{PRS}$, $f_{PRS} / 4$, $f_{PRS} / 256$ or f_{PRS} , $f_{PRS} / 16$, $f_{PRS} / 64$ is possible using bits 0 and 1 (PRM000, PRM001 or PRM010, PRM011) of prescaler mode register 00 and 01 (PRM00, PRM01). Note that when selecting the TI000 or TI001 valid edge as the count clock, $f_{sam} = f_{PRS}$.
 2. Input low level signal into RESET pin until power supply voltage is stabilized in the case of the power supply voltage rise time is slowly (more than 3.4ms).
 3. μPD78F0537/0536/0535/0534 only

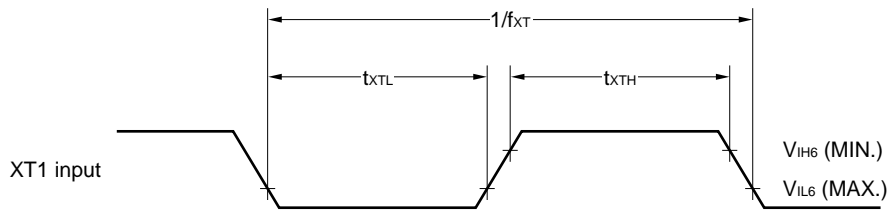
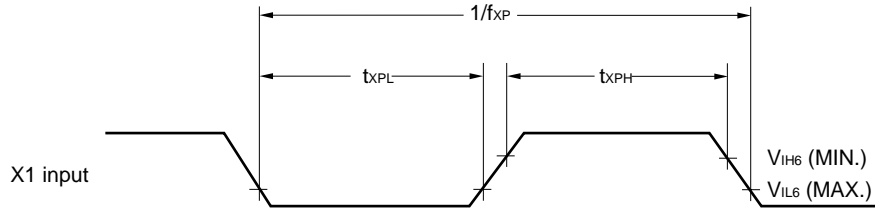


Remark The values indicated by the shaded section are only when the High-speed Ring-OSC clock is selected.

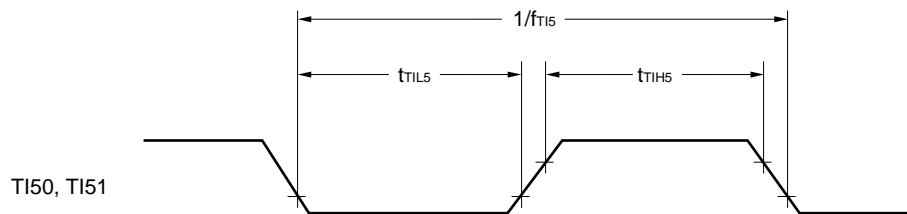
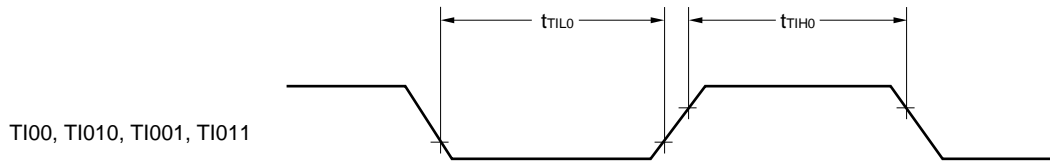
AC Timing Test Points (Excluding X1 Input)



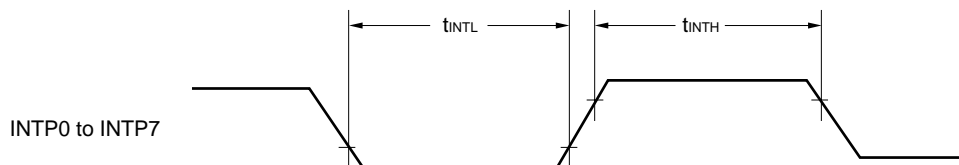
Clock Timing



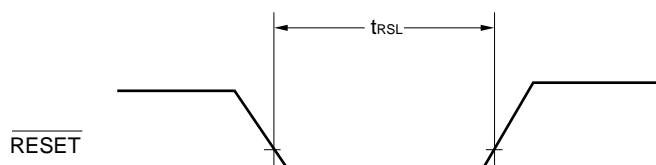
TI Timing



Interrupt Request Input Timing



RESET Input Timing



(2) Serial interface

($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} = EV_{DD} \leq 5.5\text{ V}$, $2.3\text{ V} \leq AV_{REF} \leq V_{DD} = EV_{DD}$, $V_{SS} = EV_{SS} = AV_{SS} = 0\text{ V}$)

(a) UART mode (UART6, dedicated baud rate generator output)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Transfer rate					312.5	kbps

(b) UART mode (UART0, dedicated baud rate generator output)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Transfer rate					312.5	kbps

(c) IIC0 mode

Parameter	Symbol	Normal mode		High speed mode		Unit
		MIN.	MAX	MIN.	MAX	
SCL0 clock frequency	f _{CLK}	0	100	0	400	kHz
Start/restart condition setup time ^{Note1}	t _{SU: STA}	4.8	-	0.7	-	μs
hold time	t _{HD: STA}	4.1	-	0.7	-	μs
Hold time in SCL = "L"	t _{LOW}	5.0	-	1.25	-	μs
Hold time in SCL = "H"	t _{HIGH}	5.0	-	1.25	-	μs
Data setup time (reception)	t _{SU: DAT}	0	-	0	-	μs
Data hold time (sending) ^{Note2}	t _{HD: DAT}	0.47	4.0	0.23	1.00	μs

Notes 1. The first clock pulse is generated after this period in the case of the start/restart condition.

2. The MAX of t_{HD: DAT} is normal transition value. Wait is occurred in the term of ACK(acknowledge) .

Caution Specification at $1.8\text{ V} \leq V_{DD} < 2.7\text{V}$ is not fixed.

(d) 3-wire serial I/O mode (CSI10, CSI11 master mode, $\overline{\text{SCK1n}}$...internal clock output)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
SCK1n cycle time	t_{KCY1}	$4.0 \text{ V} \leq V_{\text{DD}} \leq 5.5 \text{ V}$	100			ns
		$2.7 \text{ V} \leq V_{\text{DD}} < 4.0 \text{ V}$	200			ns
SCK1n high-/low-level width	t_{KH1} , t_{KL1}		$t_{\text{KCY1}}/2 - 10^{\text{Not1}}$			ns
SI1n setup time (to $\overline{\text{SCK1n}}\uparrow$)	t_{SIK1}		30			ns
SI1n hold time (to $\overline{\text{SCK1n}}\uparrow$)	t_{KSI1}		30			ns
Delay time from $\overline{\text{SCK1n}}\downarrow$ to SO1n output	t_{KSO1}	$C = 50 \text{ pF}^{\text{Note2}}$			40	ns

Notes 1. This is the value when the high-speed system clock (f_{XH}) is operating.

2. C is the load capacitance of the SCK1n and SO1n output lines.

(e) 3-wire serial I/O mode (CSI10, CSI11 slave mode, $\overline{\text{SCK1n}}$...external clock input)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
SCK1n cycle time	t_{KCY2}		400			ns
SCK1n high-/low-level width	t_{KH2} , t_{KL2}		T.B.D			ns
SI1n setup time (to $\overline{\text{SCK1n}}\uparrow$)	t_{SIK2}		80			ns
SI1n hold time (to $\overline{\text{SCK1n}}\uparrow$)	t_{KSI2}		50			ns
Delay time from $\overline{\text{SCK1n}}\downarrow$ to SO1n output	t_{KSO2}	$C = 50 \text{ pF}^{\text{Note}}$			120	ns

Note C is the load capacitance of the SO1n output lines.

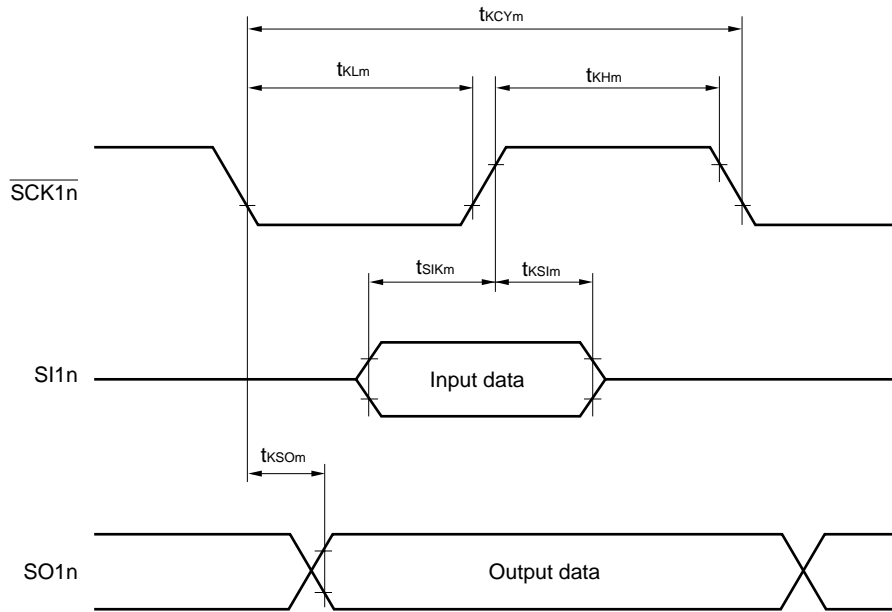
Remark n = 0 ($\mu\text{PD78F0533/0532/0531}$)

n = 0, 1 ($\mu\text{PD78F0537/0536/0535/0534}$)

Caution Specification at $1.8 \text{ V} \leq V_{\text{DD}} \leq 2.7 \text{ V}$ is not fixed.

Serial Transfer Timing

3-wire serial I/O mode:



Remark $m = 1, 2$
 $n = 0$ (μ PD78F0533/0532/0531)
 $n = 0, 1$ (μ PD78F0537/0536/0535/0534)

A/D Converter Characteristics

($T_A = -40$ to $+85^\circ\text{C}$, $1.8\text{ V} \leq V_{DD} = EV_{DD} \leq 5.5\text{ V}$, $2.3\text{ V} \leq AV_{REF} \leq V_{DD} = EV_{DD}$, $V_{SS} = EV_{SS} = AV_{SS} = 0\text{ V}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution	RES				10	bit
Overall error ^{Note1,2}	A _{INL}	$4.0\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$			± 0.4	%FSR
		$2.7\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$			± 0.6	%FSR
		$AV_{REF} < 2.7\text{ V}$			T.B.D.	%FSR
Conversion time	t _{CONV}	$4.0\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$	6.6		30	μs
		$2.7\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$	6.6		30	μs
		$AV_{REF} < 2.7\text{ V}$	11		T.B.D.	μs
Zero-scale error ^{Note1,2}	E _{ZS}	$4.0\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$			± 0.4	%FSR
		$2.7\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$			± 0.6	%FSR
		$AV_{REF} < 2.7\text{ V}$			T.B.D.	%FSR
Full-scale error ^{Note1,2}	E _{FS}	$4.0\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$			± 0.4	%FSR
		$2.7\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$			± 0.6	%FSR
		$AV_{REF} < 2.7\text{ V}$			T.B.D.	%FSR
Integral linearity error ^{Note1}	I _{LE}	$4.0\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$			± 2.5	LSB
		$2.7\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$			± 4.5	LSB
		$AV_{REF} < 2.7\text{ V}$			T.B.D.	LSB
Differential linearity error ^{Note1}	D _{LE}	$4.0\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$			± 1.5	LSB
		$2.7\text{ V} \leq AV_{REF} \leq 5.5\text{ V}$			± 2.0	LSB
		$AV_{REF} < 2.7\text{ V}$			T.B.D.	%FSR
Analog input voltage	V _{AIN}		AV _{SS}		AV _{REF}	V

Notes 1. Excludes quantization error ($\pm 1/2$ LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

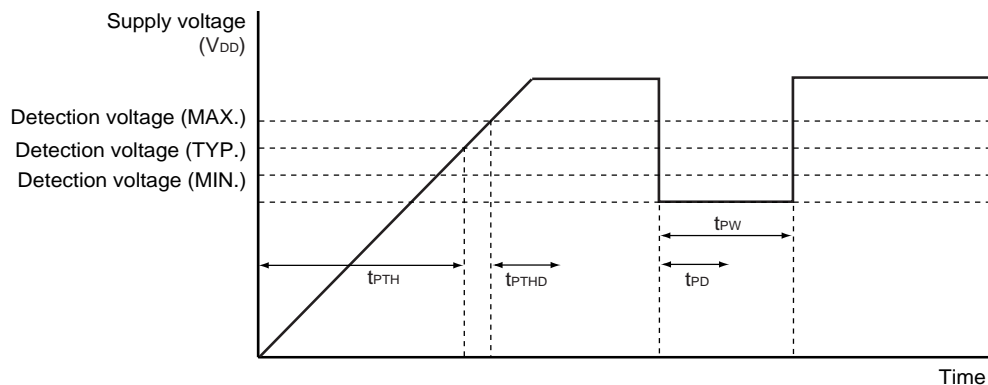
POC Circuit Characteristics ($T_A = -40$ to $+85^\circ\text{C}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	V _{POC}		1.3	1.5	1.7	V
Power supply rise time	t _{PTH}	V _{DD} : V _{poc} → 1.8 V (MIN. value of V _{DD})		75	TBD	mV/ms
Minimum pulse width	t _{PW}		T.B.D.	50		μs

Notes 1. When voltage rises, time required from detection to reset release

2. When voltage drops, time required from detection to reset occur.

POC Circuit Timing



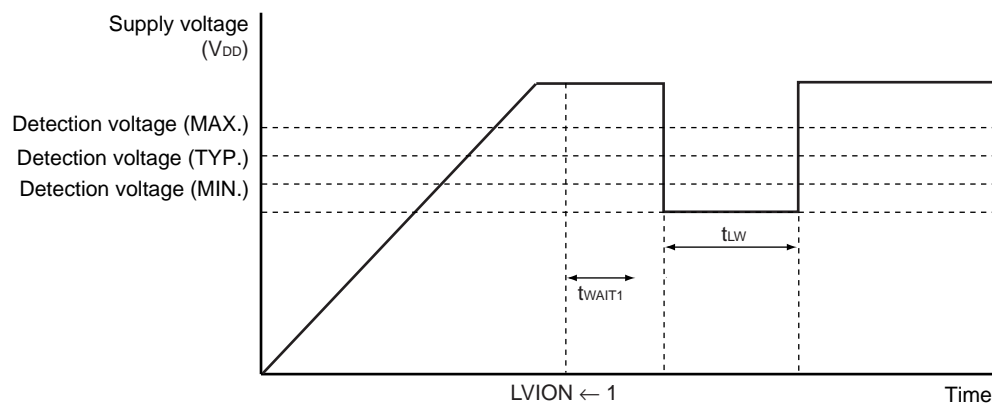
LVI Circuit Characteristics (TA = -40 to +85°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Detection voltage	Supply voltage level	V _{LV10}		4.10	4.20	4.30	V
		V _{LV11}		3.95	4.05	4.15	V
		V _{LV12}		3.81	3.91	4.01	V
		V _{LV13}		3.66	3.76	3.86	V
		V _{LV14}		3.51	3.61	3.71	V
		V _{LV15}		3.37	3.47	3.57	V
		V _{LV16}		3.22	3.32	3.42	V
		V _{LV17}		3.07	3.17	3.27	V
		V _{LV18}		2.93	3.03	3.13	V
		V _{LV19}		2.78	2.88	2.98	V
		V _{LV110}		2.63	2.73	2.83	V
		V _{LV111}		2.49	2.59	2.69	V
		V _{LV112}		2.34	2.44	2.54	V
		V _{LV113}		2.19	2.29	2.39	V
		V _{LV114}		2.05	2.15	2.25	V
		V _{LV115}		1.90	2.00	2.10	V
External input pin <small>Note1</small>	EXLVI	EXLVI < V _{DD} = EV _{DD}		1.21		V	
Minimum pulse width	t _{LW}		T.B.D.	50		μs	
Operation stabilization wait time <small>Note2</small>	T _{LWAIT1}			10	T.B.D.	μs	

- Note 1.** Using EXLVI/P120/INTP0 pin
2. Time required from setting LVION to 1 to operation stabilization

Remark V_{LV1(n-1)} > V_{LV1n} : n = 1-15

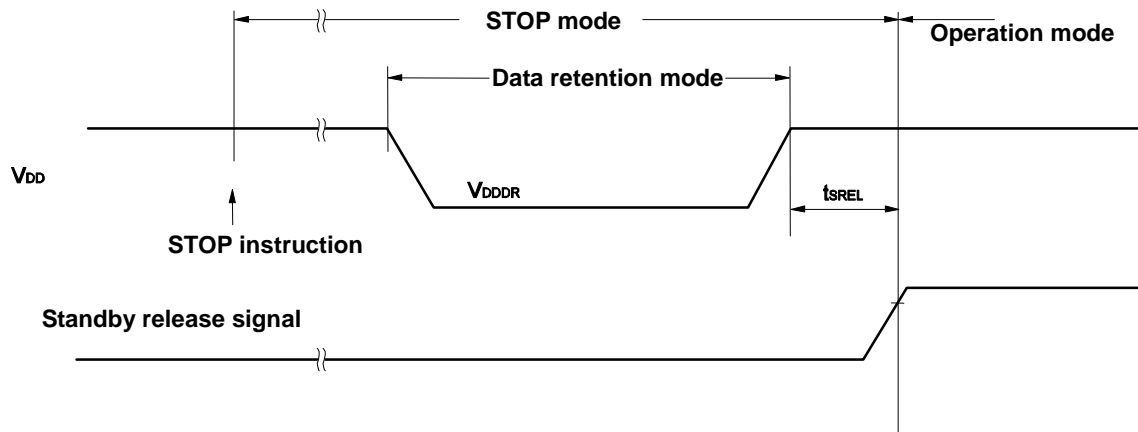
LVI Circuit Timing



Data Memory STOP Mode Low Supply Voltage Data Retention Characteristics ($T_A = -40$ to $+85^\circ\text{C}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention supply voltage	V_{DDDR}		1.3 ^{Note}		5.5	V

Note Dependence on POC detection voltage. The data is held before POC reset, but is not held after POC reset when voltage drops.



Flash Memory Programming Characteristics

($T_A = -40$ to $+85^\circ\text{C}$, $2.3\text{ V} \leq V_{DD} = EV_{DD} \leq 5.5\text{ V}$, $2.3\text{ V} \leq AV_{REF} \leq V_{DD} = EV_{DD}$, $V_{SS} = EV_{SS} = AV_{SS} = 0\text{ V}$)

(1) Basic characteristics

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
V_{DD} supply voltage	I_{DD}	$f_{XP} = 10\text{ MHz (TYP.)}, 20\text{ MHz (MAX.)}$		4.5	11.0	mA
Erase time ^{Note1}	Chip unit	T_{eraca}		20	T.B.D	ms
	Sector unit	T_{erasa}		20	T.B.D	ms
Write time	T_{wrwa}			50.	T.B.D.	μs
Number of rewrites per chip	C_{erwr}	1 erase + 1 write after erase = 1 rewrite ^{Note2}		100		time

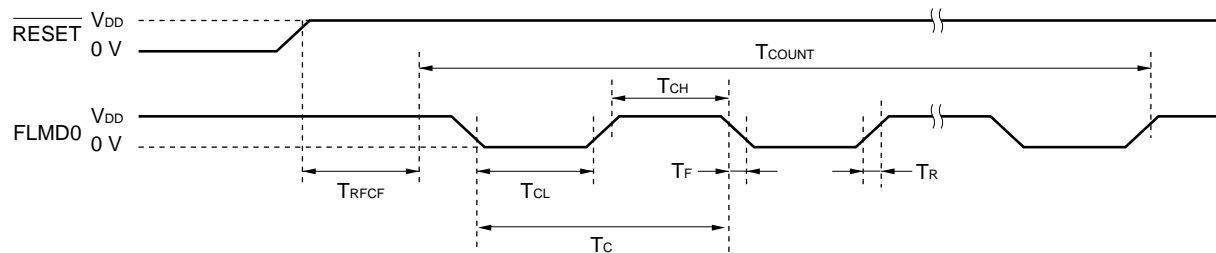
Notes 1. The prewrite time before erasure and the erase verify time (writeback time) are not included.

2. When a product is first written after shipment, "erase → write" and "write only" are both taken as one rewrite.

(2) Serial write operation characteristics

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Time from RESET \uparrow to FLMD0 count start	T_{RFCF}		T.B.D	10	T.B.D	ms
Count execution time	T_{COUNT}		T.B.D	10	T.B.D	ms
FLMD0 counter high-/low-level width	T_{CH}/T_{CL}		$T_c \times 0.45$			μs
FLMD0 counter rise/fall time	T_R/T_F		12.5			μs

Serial Write Operation



NOTES FOR CMOS DEVICES

① VOLTAGE APPLICATION WAVEFORM AT INPUT PIN

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (MAX) and V_{IH} (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (MAX) and V_{IH} (MIN).

② HANDLING OF UNUSED INPUT PINS

Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

③ PRECAUTION AGAINST ESD

A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

④ STATUS BEFORE INITIALIZATION

Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

⑤ POWER ON/OFF SEQUENCE

In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current.

The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

⑥ INPUT OF SIGNAL DURING POWER OFF STATE

Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.

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